



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-01-03</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>Giuseppe Vitali Palma</b>	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6563ATR	KKK7*UE35AA6	A	SH1A	2014-01-03
Amount		UoM	Unit type	ST ECOPACK Grade
130.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DSO	8.6X3.9X1.52	16	gull wing
Comment	Package: SO 14 .15 TO JEDEC MS-012		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

Querylist: REACH-20th JUNE 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKK7*UE35AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.641	mg	supplier	die	Silicon (Si)	7440-21-3		3.542	mg	972810	27246
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.02	mg	5493	154
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.011	mg	3021	85
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.048	mg	13183	369
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	549	15
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	4944	138
Leadframe	Copper & its alloys	35.014	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.868	mg	995830	268215
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.016	mg	457	123
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.029	mg	828	223
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.093	mg	2656	715
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.006	mg	171	46
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	57	15
Die attach	Other Organic Materials	0.717	mg	supplier	glue	Silver (Ag)	7440-22-4		0.359	mg	500697	2762
Die attach				supplier	glue	Aluminium (Al)	Proprietary		0.251	mg	350070	1931
Die attach				supplier	glue	acrylic resin	Proprietary		0.036	mg	50209	277
Die attach				supplier	glue	Ethylene glycol dicyclopentenyl ether acrylate	65983-31-5		0.057	mg	79498	438
Die attach				supplier	glue	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.007	mg	9763	54
Die attach				supplier	glue	Butadiene copolymer	68891-50-9		0.007	mg	9763	54
Bonding wire	Other inorganic materials	0.077	mg	supplier	wire	Copper (Cu)	7440-50-8		0.077	mg	1000000	592
encapsulation	Other Organic Materials	90.551	mg	supplier	mold compound	Silica, vitreous	60676-86-0		79.412	mg	876986	610862
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		3.622	mg	40000	27862
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		3.622	mg	40000	27862
encapsulation				supplier	mold compound	phenol resin	Proprietary		2.717	mg	30005	20900
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.272	mg	3004	2092
encapsulation				supplier	mold compound	additive	Proprietary		0.906	mg	10005	6969